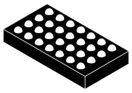
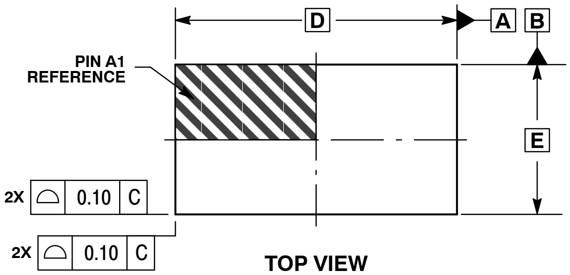
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



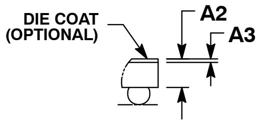
SCALE 4:1

WLCSP28, 3.1x1.65, 0.4P
CASE 567KR
ISSUE O

DATE 23 SEP 2014



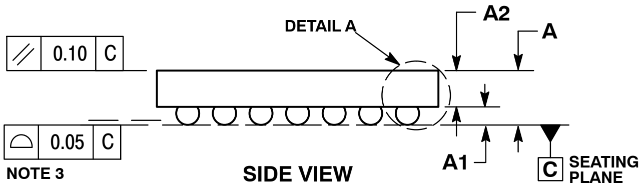
TOP VIEW



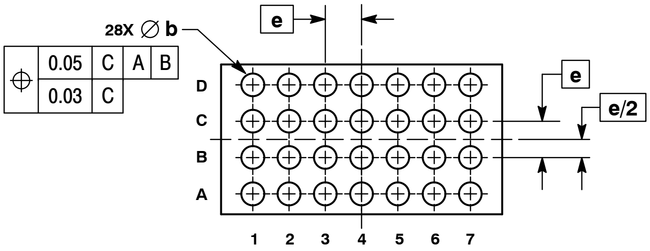
DETAIL A

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS MIN	MILLIMETERS MAX
A	---	0.60
A1	0.17	0.23
A2	0.33	0.39
A3	0.02	0.04
b	0.24	0.28
D	3.10 BSC	
E	1.65 BSC	
e	0.40 BSC	

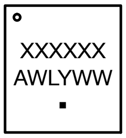


SIDE VIEW



BOTTOM VIEW

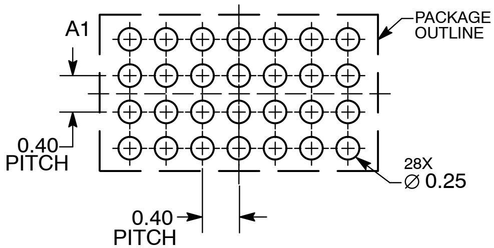
GENERIC MARKING DIAGRAM*



A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**WLCSP28, 3.1X1.65, 0.4P**	**PAGE 1 OF 1**